

ABSTRACT OF THE DISCLOSURE

A package substrate with a microelectronic die mounted to a first side and contact formations attached to a second side thereof. A stress compensation layer is formed on the first surface between the contact formations. The semiconductor package is attached to a circuit board leaving an air space between the stress compensation layer and the circuit board. The stress compensation layer reduces stress on the contact formations and increases solder joint reliability. Also a method of forming an electronic assembly including depositing a stress relief layer on a package substrate and attaching the substrate to a circuit board.